Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3004	(electron adj microscopy) and microstructure	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/11 13:59
L2	20	1 and (plurality near3 image)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/11 14:05
L3	5	2 and (stress or stresses)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/01/11 14:04
S1	3000	(electron adj microscopy) and microstructure	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/11 13:59
S2	11	S1 and (microstructure adj device)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/11 13:57
S3	9	S2 and (stress or stresses)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/01/11 14:00
S4	3	S3 and conductive	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/01/10 16:57
S5	78	S1 and (stress or stresses) near4 condition	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/10 16:54
S6	78	S5 and microstructure	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/10 16:54
S7	1	S6 and (microstructure adj device)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/11 12:07
S8	11	S6 and conductive	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/01/10 17:05
S9	4	S8 and plurality	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/01/10 17:08

S10	4	S8 and image	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/10 17:11
S11	3	"5124645"	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/01/11 11:42
S12	3004	(electron adj microscopy) and microstructure	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/11 11:42
S13	38	S12 and (microstructure near4 (stress or stresses))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/11 11:44
S14	11	S13 and cross-section	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/11 11:54
S15	3004	(electron adj microscopy) and microstructure	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/11 12:07
S16	22	S15 and (microstructure near4 dielectric)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/11 12:08
S17	6	S16 and (stress or stresses)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/01/11 13:53